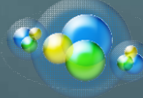


TEHCET

Electronics Materials Information



Sputtering Targets

for Semiconductor Manufacturing Applications

*TEHCET's Market & Supply Chain
Critical Materials Report™*

By Terry A. Francis

Edited by L. Shon-Roy

TEHCET Group

a TEHCET CA LLC Company

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

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